DEVICE FOR ARRANGING CONDUCTIVE BALLS

ABSTRACT

A device for arranging conductive balls is disclosed here. The device includes an arrangement jig configured such that support holes are formed in a predetermined arrangement pattern therein, a ball feeding head configured to feed a group of balls, and a transfer means configured to move the ball feeding head along the top surface of the arrangement jig. The conductive balls are put into the support holes by performing the operation of moving the group of balls along the top surface of the arrangement jig. Discharge holes are formed at a location outside an area, across which the group of balls passes during the operation of moving the group of balls, within the top surface of the arrangement jig. The group of balls is moved to the location at which the discharge holes have been formed when the group of balls is discharged.

(No figure)

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